# **MCR100 Series**

# **Sensitive Gate Silicon Controlled Rectifiers**

# **Reverse Blocking Thyristors**

PNPN devices designed for high volume, line-powered consumer applications such as relay and lamp drivers, small motor controls, gate drivers for larger thyristors, and sensing and detection circuits. Supplied in an inexpensive plastic TO-226AA package which is readily adaptable for use in automatic insertion equipment.

#### **Features**

- Sensitive Gate Allows Triggering by Microcontrollers and Other Logic Circuits
- Blocking Voltage to 600 V
- On-State Current Rating of 0.8 A RMS at 80°C
- High Surge Current Capability 10 A
- Minimum and Maximum Values of IGT, VGT and IH Specified for Ease of Design
- Immunity to dV/dt 20 V/µsec Minimum at 110°C
- Glass-Passivated Surface for Reliability and Uniformity
- Pb-Free Packages are Available\*



# ON Semiconductor®

http://onsemi.com

# SCRs 0.8 A RMS 100 thru 600 V





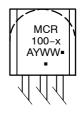




STRAIGHT LEAD BULK PACK

BENT LEAD TAPE & REEL AMMO PACK

## **MARKING DIAGRAM**



x = Specific Device CodeA = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT				
1	Cathode			
2	Gate			
3	Anode			

## **ORDERING INFORMATION**

See detailed ordering and shipping information on page 5 of this data sheet.

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### MCR100 Series

### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Notes 1 and 2) $(T_J = -40 \text{ to } 110^{\circ}\text{C}, \text{ Sine Wave, } 50 \text{ to } 60 \text{ Hz; } R_{GK} = 1 \text{ k}\Omega) \\ MCR100-3 \\ MCR100-4 \\ MCR100-6 \\ MCR100-8 \\ MCR100-8$	V <sub>DRM,</sub> V <sub>RRM</sub>	100 200 400 600	V
On-State RMS Current, (T <sub>C</sub> = 80°C) 180° Conduction Angles	I <sub>T(RMS)</sub>	0.8	Α
Peak Non-Repetitive Surge Current, (1/2 Cycle, Sine Wave, 60 Hz, T <sub>J</sub> = 25°C)	I <sub>TSM</sub>	10	Α
Circuit Fusing Consideration, (t = 8.3 ms)	l <sup>2</sup> t	0.415	A <sup>2</sup> s
Forward Peak Gate Power, (T <sub>A</sub> = 25°C, Pulse Width ≤ 1.0 μs)	$P_{GM}$	0.1	W
Forward Average Gate Power, (T <sub>A</sub> = 25°C, t = 8.3 ms)	P <sub>G(AV)</sub>	0.01	W
Forward Peak Gate Current, (T <sub>A</sub> = 25°C, Pulse Width ≤ 1.0 μs)	I <sub>GM</sub>	1.0	А
Reverse Peak Gate Voltage, ( $T_A$ = 25°C, Pulse Width $\leq 1.0 \mu s$ )	$V_{GRM}$	5.0	V
Operating Junction Temperature Range @ Rate V <sub>RRM</sub> and V <sub>DRM</sub>	TJ	-40 to 110	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Thermal Resistance, Junction-to-Case Junction-to-Ambient	$R_{ hetaJC} \ R_{ hetaJA}$	75 200	°C/W	
Lead Solder Temperature (<1/16" from case, 10 secs max)	T <sub>L</sub>	260	°C	

# ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Peak Repetitive Forward or Reverse Blocking Current (Note 3) $T_C = 25^{\circ}C$	I <sub>DRM</sub> , I <sub>RRM</sub>	_	-	10	μΑ
$(V_D = Rated V_{DRM} \text{ and } V_{RRM}; R_{GK} = 1 \text{ k}\Omega)$ $T_C = 110^{\circ}\text{C}$		-	-	100	
ON CHARACTERISTICS		- <del>-</del> -		-	=
Peak Forward On-State Voltage* (I <sub>TM</sub> = 1.0 A Peak @ T <sub>A</sub> = 25°C)	$V_{TM}$	-	-	1.7	V
Gate Trigger Current (Note 4) $T_C = 25^{\circ}C$ (V <sub>AK</sub> = 7.0 Vdc, R <sub>L</sub> = 100 $\Omega$ )	I <sub>GT</sub>	-	40	200	μΑ
Holding Current (Note 3) $T_C = 25^{\circ}C$ (V <sub>AK</sub> = 7.0 Vdc, Initiating Current = 20 mA, R <sub>GK</sub> = 1 k $\Omega$ ) $T_C = -40^{\circ}C$	lΗ	-	0.5 -	5.0 10	mA
Latch Current (Note 4) $T_C = 25^{\circ}C$ $(V_{AK} = 7.0 \text{ V}, \text{ Ig} = 200 \mu\text{A})$ $T_C = -40^{\circ}C$	ΙL	-	0.6 -	10 15	mA
Gate Trigger Voltage (Note 4) $T_C = 25^{\circ}C$ $(V_{AK} = 7.0 \text{ Vdc}, R_L = 100 \Omega)$ $T_C = -40^{\circ}C$	V <sub>GT</sub>	-	0.62 -	0.8 1.2	V
DYNAMIC CHARACTERISTICS					
Critical Rate of Rise of Off–State Voltage ( $V_D$ = Rated $V_{DRM}$ , Exponential Waveform, $R_{GK}$ = 1 $k\Omega$ , $T_J$ = 110°C)	dV/dt	20	35	-	V/μs
Critical Rate of Rise of On–State Current (I <sub>PK</sub> = 20 A; Pw = 10 μsec; diG/dt = 1 A/μsec, Igt = 20 mA)	di/dt	_	-	50	A/μs

<sup>\*</sup>Indicates Pulse Test: Pulse Width  $\leq$  1.0 ms, Duty Cycle  $\leq$  1%.

V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

<sup>2.</sup> See ordering information for exact device number options.

<sup>3.</sup>  $R_{GK}$  = 1000  $\Omega$  included in measurement.

<sup>4.</sup> Does not include  $R_{GK}$  in measurement.